TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT Docket No. BUR920010167US1 (Under 37 CFR 1.97(b) or 1.97(c)) Aday, et 🐒 In Re Application/Of: FEB 2 5 2002 Serial No. Examiner Filing Date **Group Art Unit** 09/683,733 02/07/02 Title: CUSTOM PRICING SYSTEM AND METHOD RECEIVED WAR 0 8 2002 Address to: **Assistant Commissioner for Patents** Technology Center 2100 Washington, D.C. 20231 37 CFR 1.97(b) The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the ments, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114. 37 CFR 1.97(c) The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of: the statement specified in 37 CFR 1.97(e); OR the fee set forth in 37 CFR 1.17(p).

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In Re Application: Aday, et al. FEB 2 5 2002								
Serial No.	Serial No. Filing Date FADEMAR Examiner Group Art Unit							
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	(Only complete if Applicant el	ects to pay the fee set forth in 37 C	CFR 1.17	7(p))				
□ A check in the amount of is attached.  □ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No.09-0456 as described below. A duplicate copy of this sheet is enclosed.  □ Charge the amount of □ Credit any overpayment. □ Charge any additional fee required.  Certificate of Transmission by Facsimile*  Certificate of Mailing by First Class Mail  □ Certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. ) on  □ Credit any overpayment. □ Certificate of Mailing by First Class Mail  □ Certify that this document and fee is being deposited on 02/12/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.  □ Charge any additional fee required.  □ Certificate of Mailing by First Class Mail  □ Certify that this document and fee is being deposited on 02/12/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.  □ Commissioner for Patents, Washington, D.C. 20231.  □ Commissioner for Patents, Washington, D.C. 20231.  □ Commissioner for Patents, Washington, D.C. 20231.								
Typed or Printed Name of Person Signing Certificate  Typed or Printed Name of Person Mailing Certificate  Typed or Printed Name of Person Mailing Certificate								
*This certificate may only be used if paying by deposit account.  Dated: 211/D2  Signature  Richard M. Kotulak  Registration No. 27,712  International Business Machines Corporation Intellectual Property Law - Mail 972E  1000 River Street  Essex Junction, VT 05452  CC:								

## IN THE WHITEDASPATES PATENT AND TRADEMARK OFFICE

In re application of: Aday et al.

: Date: January 4, 2002

Serial Number: Concurrent

Group Art Unit:

Filed: Concurrent

Examiner:

Title: Custom Pricing System and Method

: IBM CORPORATION

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Intellectual Property Law

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: 1000 River Street, 972E

Essex Junction, Vermont OF Annology Center 2100

INFORMATION DISCLOSURE STATEMENT (IDS) UNDER 37 CFR 1.97

**Commissioner For Patents** Washington, D. C. 20231

Dear Sir:

The attached Form PTO-1449, and any attached foreign patent office search report, provides a listing of information which may be relevant to the subject application. This IDS is not intended as a representation that better art is not available, nor that the information provided is prior art.

This IDS is submitted under:

X 37 CFR 1.97(b) - No Fee.
37 CFR 1.97(c) - No Fee. Each item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application. This communication is dated, which is not more than 3 months prior to the mailing of this statement.
37 CFR 1.97(c) - Fee.
37 CFR 1.97(d) - Fee, Certification & Petition.

The Commissioner is authorized to charge payments of any associated fees required under 37 CFR 1.17(p) and (i) (1) to Deposit Account No. 09-0456.

Respectfully submitted,

By:

John W. LaBatt

Registration No. 48,301

Telephone No.: (518) 449-0044

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